

INFORMATION ONLY NOTIFICATION

The following ION PCN Q3083105 is a follow up PCN to the formally distributed Final PCN 20042803-A, which announced the Bump Process/Method: from High Lead Bump (95% Pb, 5% Sn) to Lead Free Bump (Cu wire bumping 99.99% Cu).

This is to inform you that a minor change is being made to the following product(s). This notification is for your information only.

If you have any questions concerning this change, please contact:

Technical Contact:

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Implementation of change:

Expected 1st Device Shipment Date: 2008/12/15

Earliest Year/Work Week of Changed Product: 0851

Change Type Description: Information Only

Description of Change (From): Base SSOT-6 devices with 95% Pb, 5% Sn bumps will be obsolete and replaced with SSOT-6 devices with Cu stud and can be identified with _F077 flow code nomenclature.

Description of Change (To): Flow code _F077 to identify active SSOT-6 parts with Cu stud process. The base devices, the non _F077 parts with 95% Pb, 5% Sn bumps, are being obsolete.

Reason for Change : The flow code _F077 is to replace the base product ID. Both the base part and the flow code devices are electrically identical.

Change From

Base Product ID	Status Code	Replacement / Flow Product ID	Status Code
FDC6036P	L	FDC6036P_F077	S
FDC796N	L	FDC796N_F077	S
FDC6000NZ	K	FDC6000NZ_F077	S
FDC6020C	K	FDC6020C_F077	S
FDC697P	K	FDC697P_F077	S
FDC699P	K	FDC699P_F077	S

Product Id Description : Fairchild Semiconductor's selected products in the SSOT-6 FLMP package. Please refer to the table that suggests the affected based parts and their replacement. Both the base part and the flow code devices are electrically identical.

Affected FSIDs :

FDC6000NZ_F077	FDC6020C_F077	FDC6036P_F077
FDC697P_F077	FDC699P_F077	FDC796N_F077